ememory

A Leading Logic NVM Company

IPR Notice

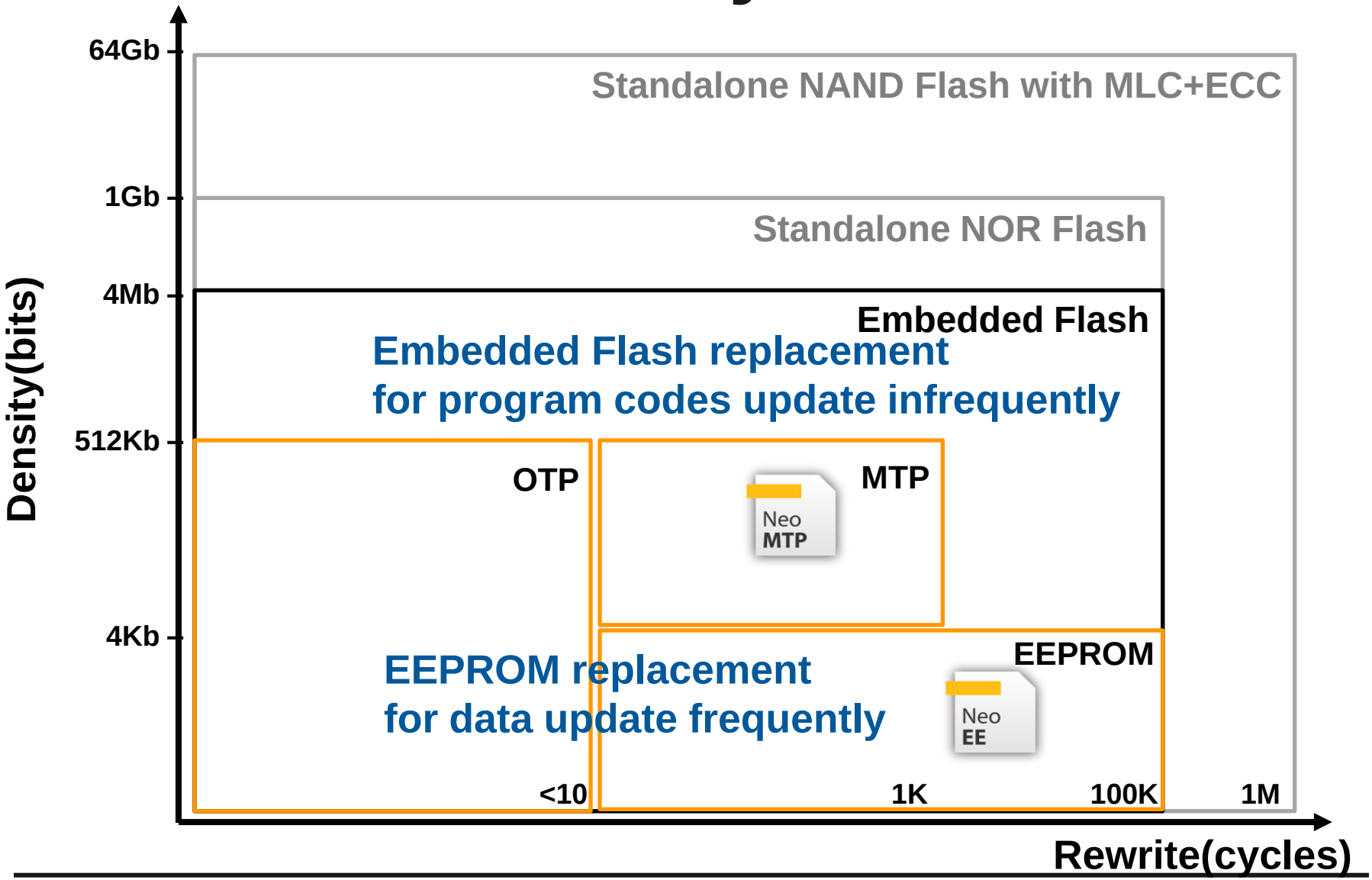
Cautionary Statement

This presentation contains forward-looking statements, which are subject to risk factors associated with semiconductor and intellectual property business. It is believed that the expectations reflected in these statements are reasonable. But they may be affected by a variety of variables, many of which are beyond our control. These variables could cause actual results or trends to differ materially which include, but are not limited to: wafer price fluctuation, actual demand, rapid technology change, delays or failures of customers' tape-outs into wafer production, our ability to negotiate, monitor and enforce agreements for the determination and payment of royalties, any bug or fault in our technology which leads to significant damage to our technology and reputation, actual or potential litigation, semiconductor industry cycle and general economic conditions. Except as required by law, eMemory undertakes no obligation to update or revise any forward-looking statements, whether as a result of new information, future events, or otherwise.

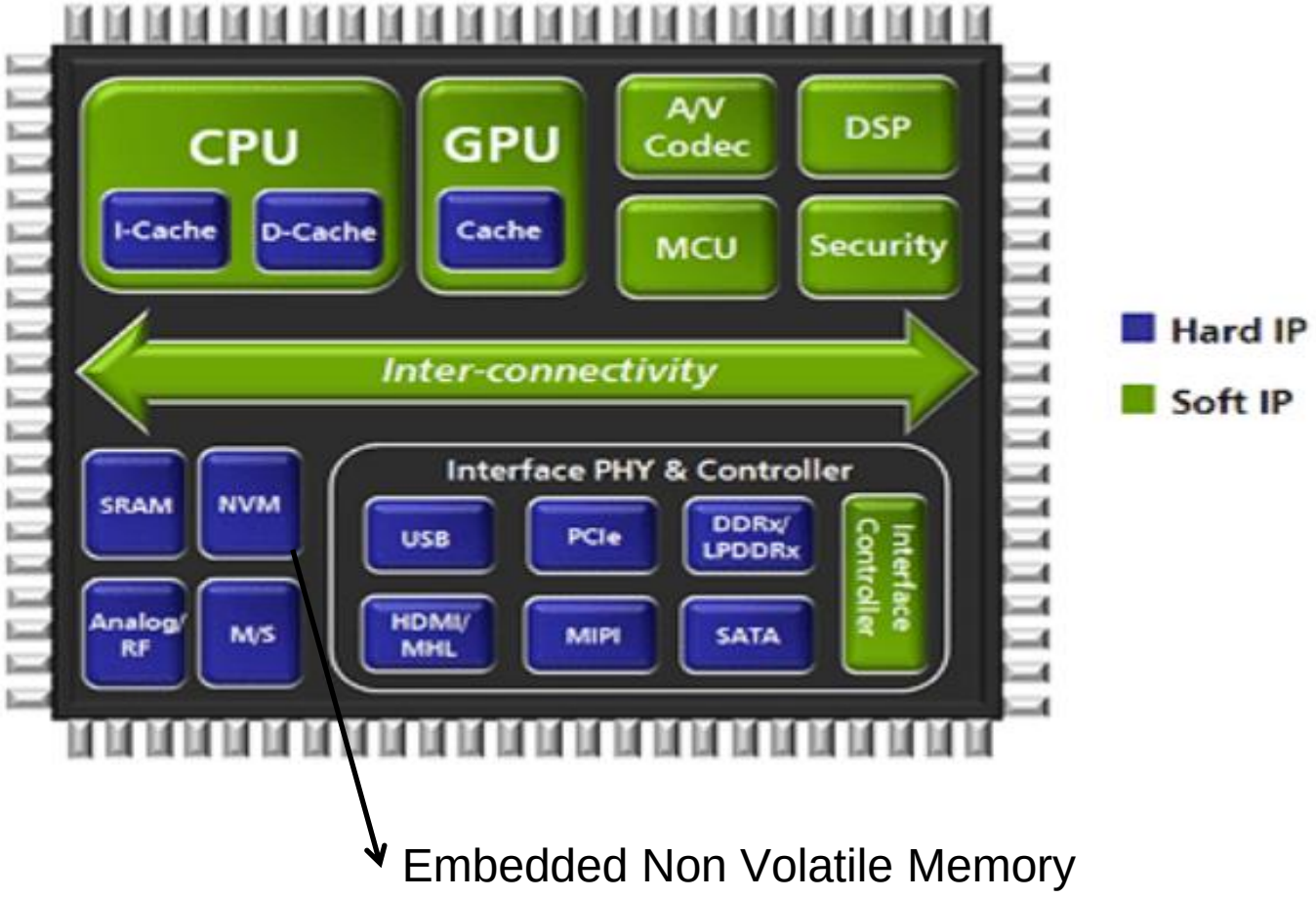
Outline

- **Business Model**
- **Review of Operations**
- **Growth Opportunity and Future Outlook**
- **Q & A**

Nonvolatile Memory Classifications



SOC Block Diagram



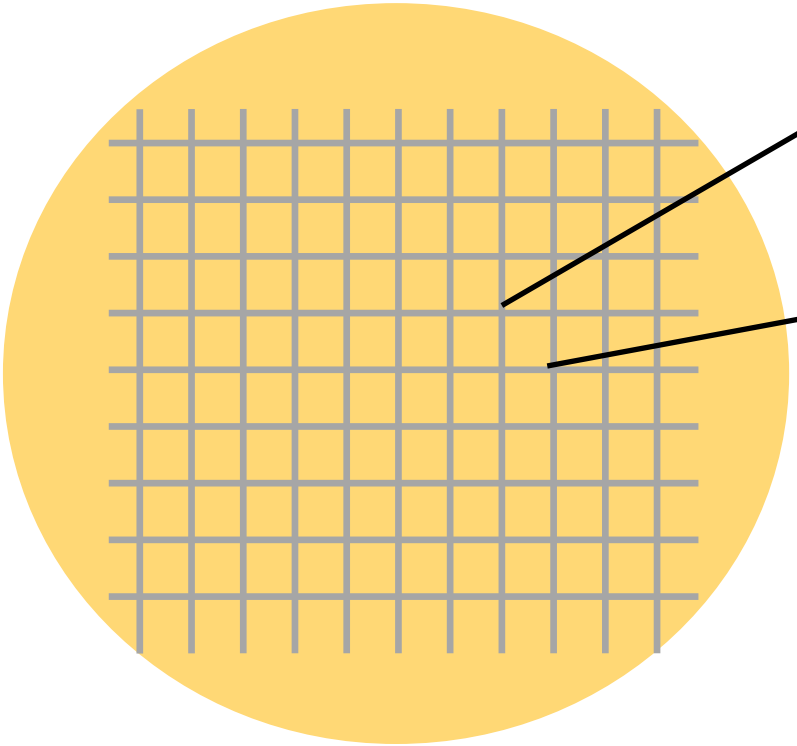
Source : tsmc

Embedded NVM Technologies

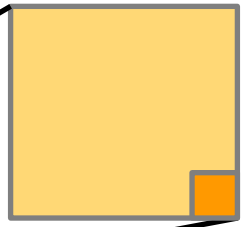
	ROM	eFuse (OTP)	Antifuse (OTP)	CMOS Floating Gate (OTP)	CMOS Floating Gate (MTP)	Embedded Flash
Cell Structure	Transistor	Poly Fuse	Antifuse	Floating Gate	Floating Gate	Floating Gate
Standard CMOS Compatible	Yes	Yes	Yes	Yes	Yes	No
Bitcell Area	< 1	50	1	2	4	1
Endurance	No	No	< 10	< 10	10K-100K	100-1000K
Density	4Kb-1Mb	256bit-4Kb	16bit-1Mb	16Kb-1Mb	1Kb-2M	64Kb-4Mb
Security	Low	Low	High	High	High	High
Additional Steps	None	None	None	None	None	+10 Mask

- ROM not programmable, eFuse cannot scale beyond 16Kb, embedded flash expensive and cannot scale after 40 nm
- eMemory's IPs: OTP (antifuse, floating gate) and MTP (floating gate)

Considerations for IP Adoption



Customer Product



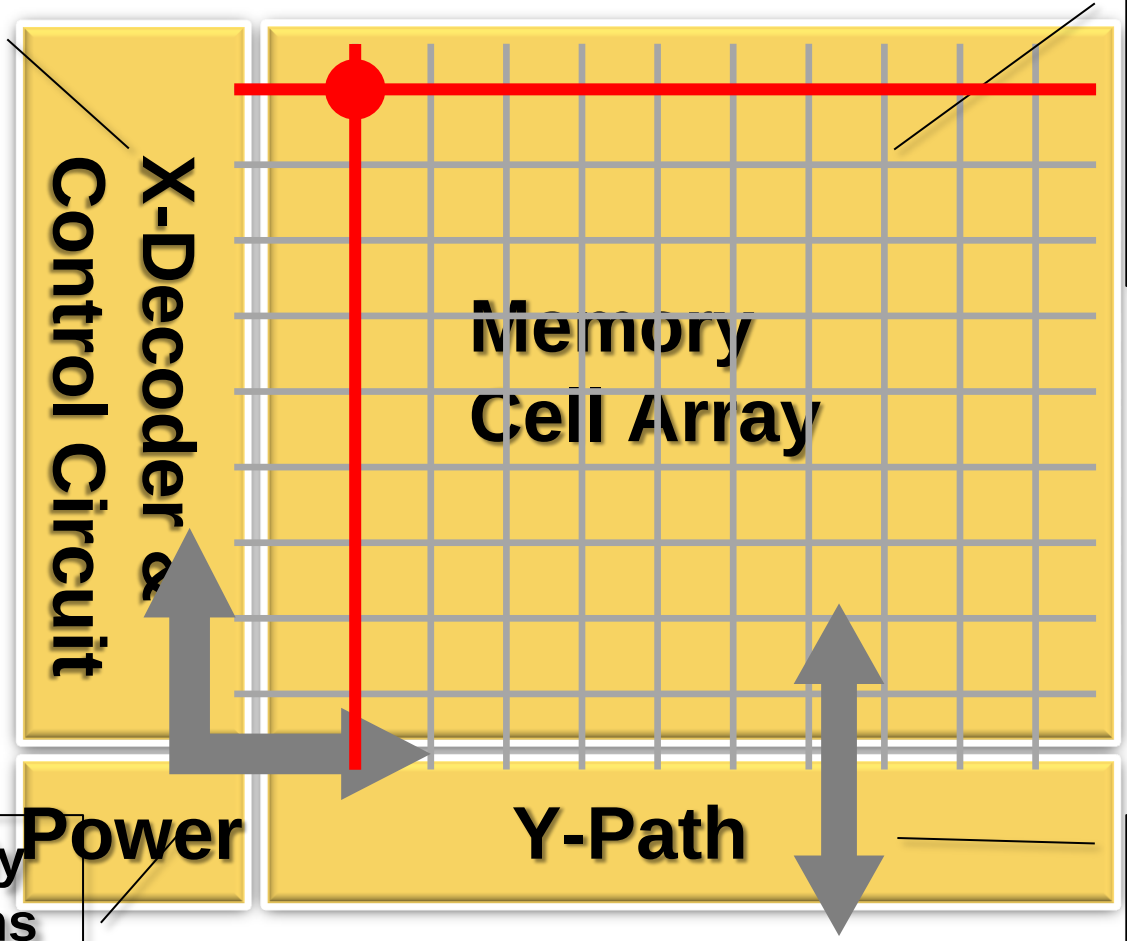
Generally,
IP size is less than
10% of product size

IP

Customers Request

1. 100% IP Reliability
2. No Mask Adder
3. Low Testing Cost
4. On call Service
5. Acceptable IP Size

Inside Nonvolatile Memory IP



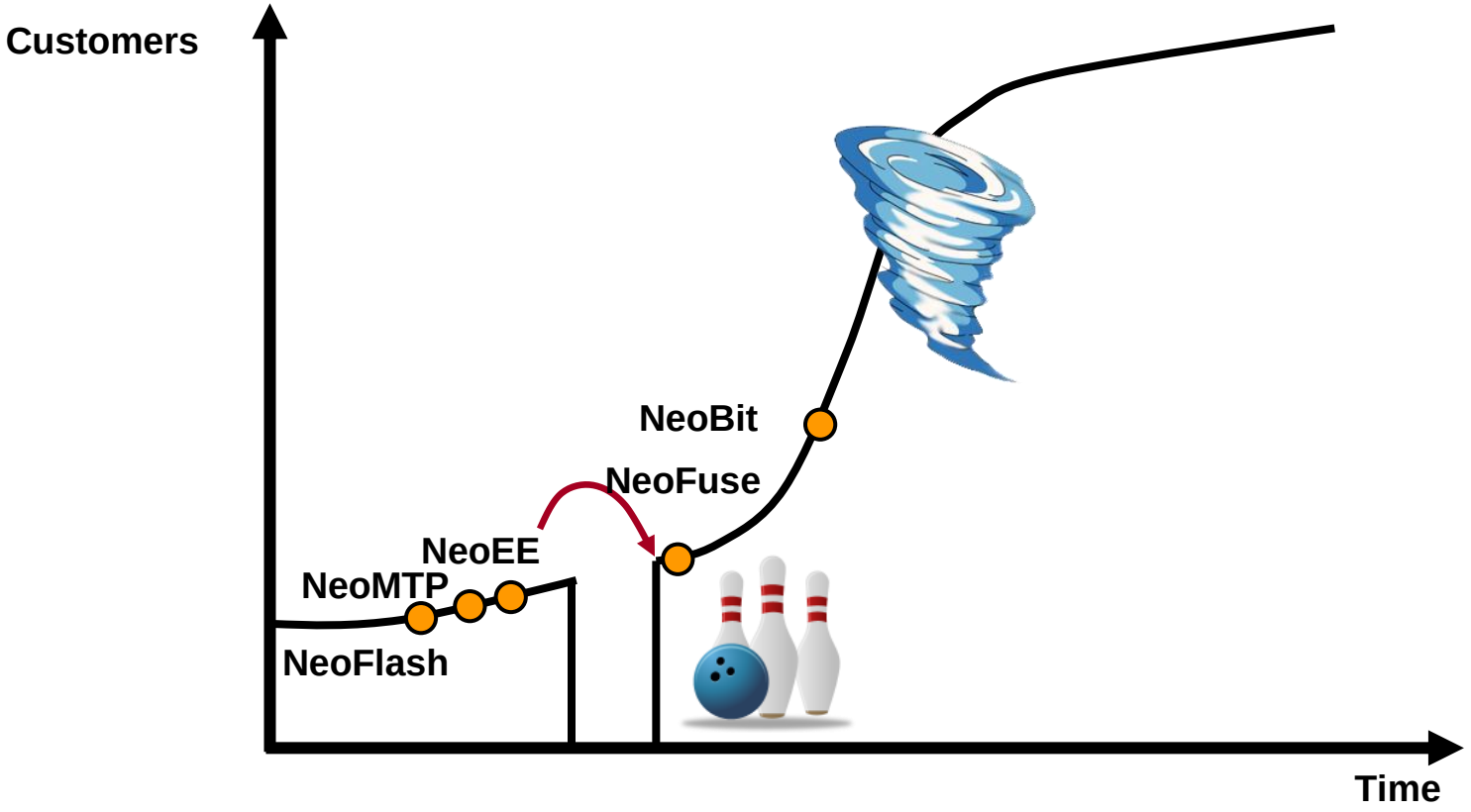
Program, Erase and Read operation control

Where data is stored. Each cross point has a memory cell.

Power supply for operations

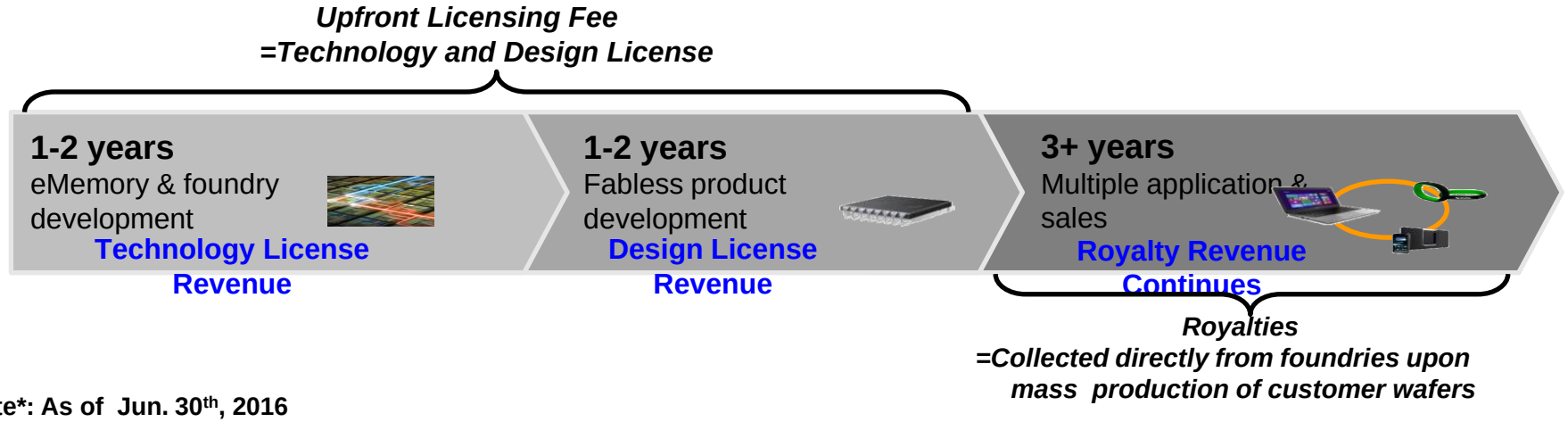
Data input & output

Crossing the Chasm



Business Model

- **Founded in 2000. First customer engaged in 2002. Achieved profitability in 2005 and IPO in 2011. The largest logic non-volatile memory IP company, 228 employees (159 R&D)*.**
- **Since its IPO, the company initiated no new fund raising or bank debt, and has distributed in excess of 100% of earnings in cash dividends.**
- **Growth Indices: 1) No. of on-going technology platforms**
  2) No. of design licenses
  3) Royalty



Note*: As of Jun. 30th, 2016

Worldwide Customers

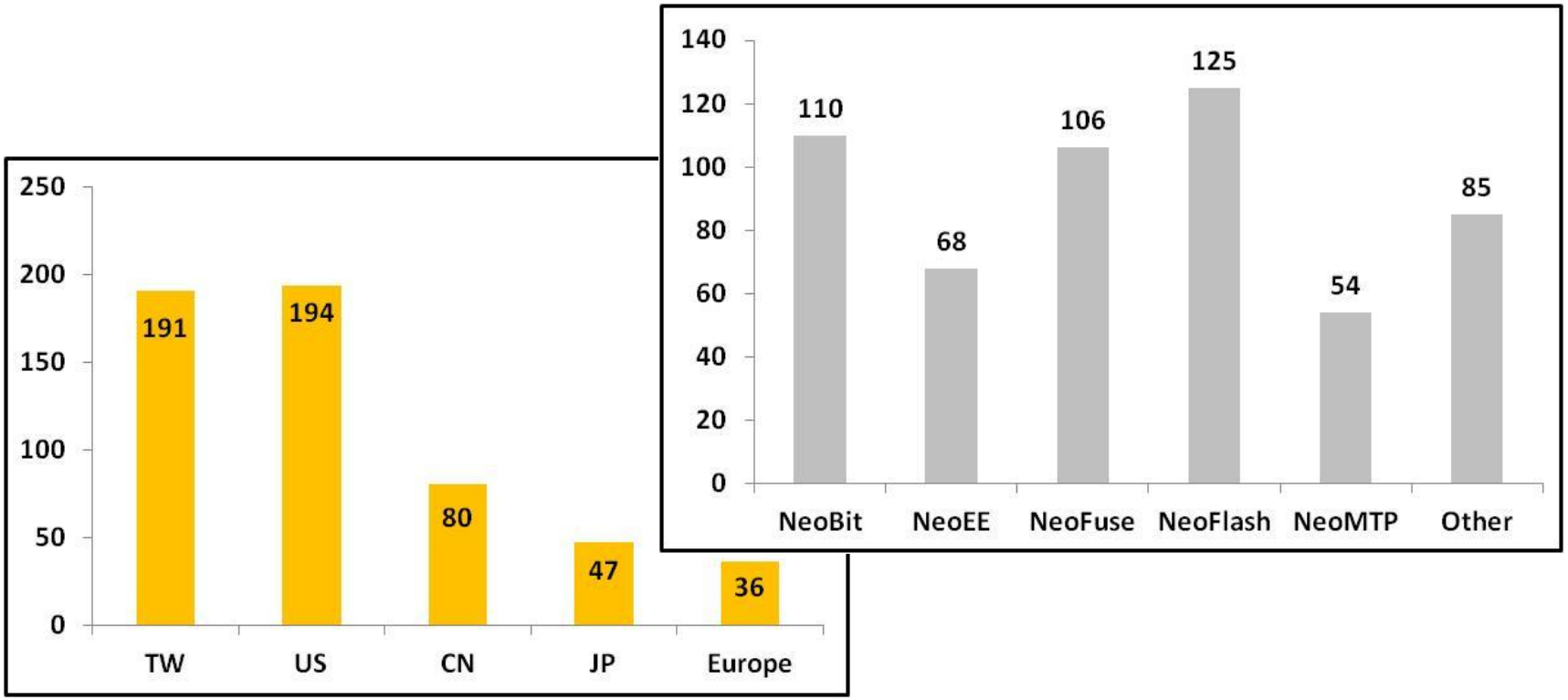
	Taiwan	China	Korea	Japan	North America	Europe	Others
Foundry	**5**	**7**	**3**	**2**	**1**	**1**	**1**
IDM	**0**	**0**	**0**	**8**	**2**	**1**	**0**
Fabless	**251**	**409**	**59**	**47**	**191**	**107**	**42**

Foundry

IDM

Patent Portfolio

	Q1 16	Q2 16	Diff.
Pending	185	193	+ 8
Issued	345	355	+ 10
Total	530	548	+ 18

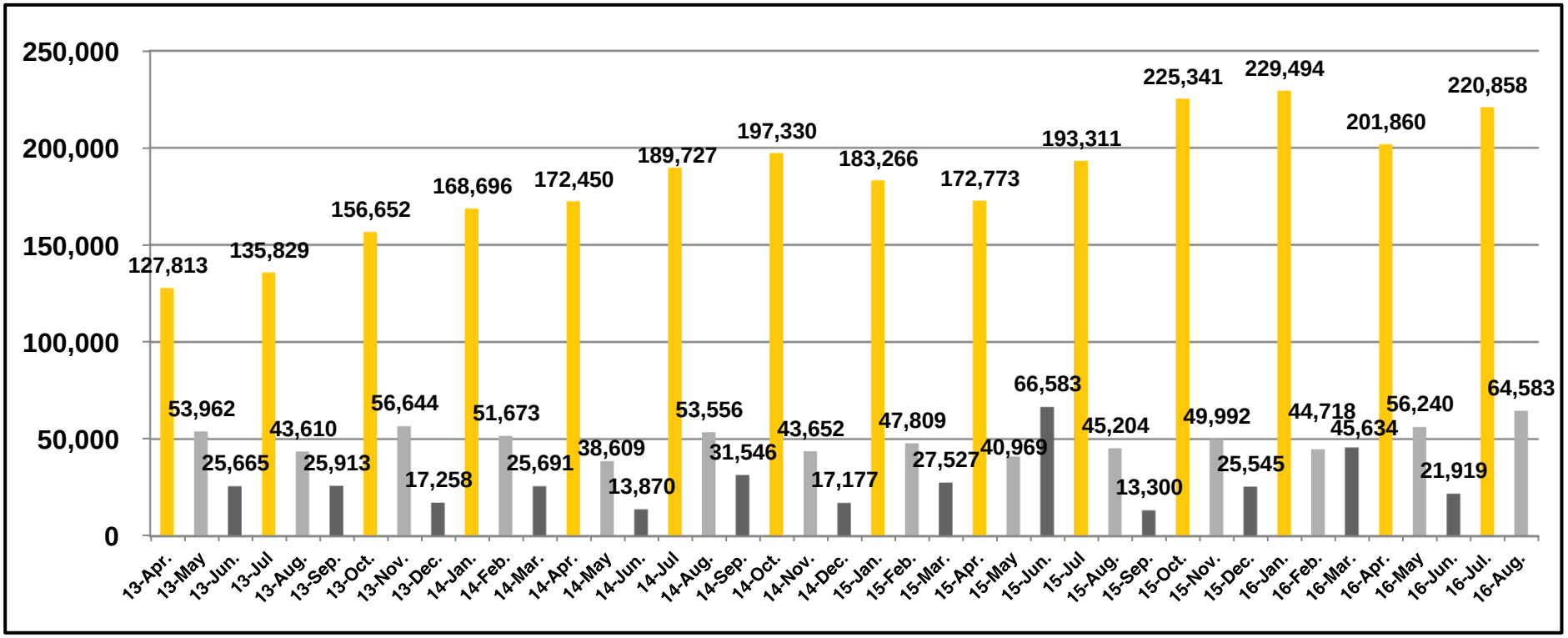


Note*: As of Jun. 30th, 2016

Quarterly Revenue Pattern

- **The quarterly royalty from most of foundries are collected at first month of each quarter and from some other foundries are collected at second month, and none at third month.**

Unit：NTD Thousands



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Q2 Revenue Breakdown

Unit: NTD thousands

	Q2 2016	Q1 2016	QoQ	Q2 2015	YoY	H1 2016	H1 2015	YoY
Licensing	77,715	85,976	-9.61%	95,982	-19.03%	163,691	160,038	2.28%
Royalty	202,304	233,870	-13.50%	184,343	9.74%	436,174	378,889	15.12%
Total	280,019	319,846	-12.45%	280,325	-0.11%	599,865	538,927	11.31%

Unit: Number of contracts

		Q2 2016	Q1 2016	2015	2014
Technology Licenses		14	13	28	21
Design Licenses	NRE	14	13	57	82
	Usage	96	69	349	363

Financial Income Statement

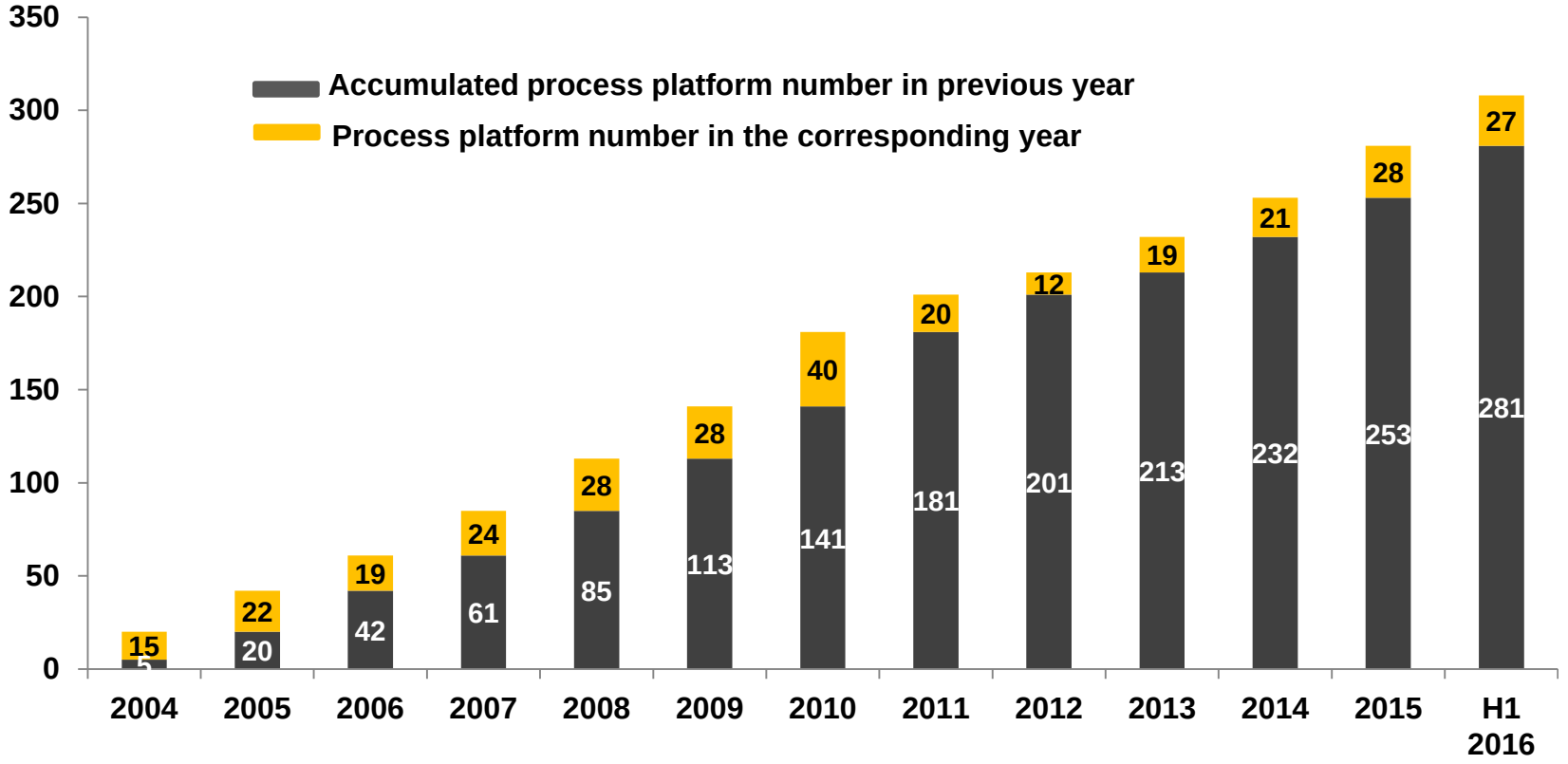
(Unit: NTD thousands)	Q2 2016	Q1 2016	% change	Q2 2015	% change
Revenue	280,019	319,846	-12.5%	280,325	-0.1%
Gross Margin	100%	100%	-	100%	-
Operating Expenses	163,276	177,088	-7.8%	141,435	15.4%
Operating Margin	41.7%	44.6%	-2.9ppts	49.5%	-7.8ppts
Net Income	106,245	166,012	-36.0%	130,297	-18.5%
Net Margin	37.9%	51.9%	-14.0ppts	46.5%	-8.6ppts
EPS (Unit: NTD)	1.40	2.19	-36.1%	1.72	-18.6%
ROE	24.5%	34.9%	-10.4ppts	30.9%	-6.4ppts

Technology License

Unit: Number of contract

Year	2013	2014	2015	H1 2016
License number	19	21	28	27

Note: The terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.



Current Technology Development Platforms

- Total (As of June) : 108
- 20 for NeoBit, 46 for NeoFuse, 21 for NeoEE, and 21 for NeoMTP.

	7/10nm	14/16nm	28nm	40nm	55/65nm	80/90nm	0.11~ 0.13um	0.15~ 0.18um	>0.25 um
NeoBit	-	-	-	-	-	-	6	13	1
NeoFuse	2	3	9	6	11	5	7	3	-
NeoFlash	-	-	-	-	-	-	-	-	-
NeoEE	-	-	-	-	-	1	5	15	-
NeoMTP	-	-	-	-	2	2	6	11	-

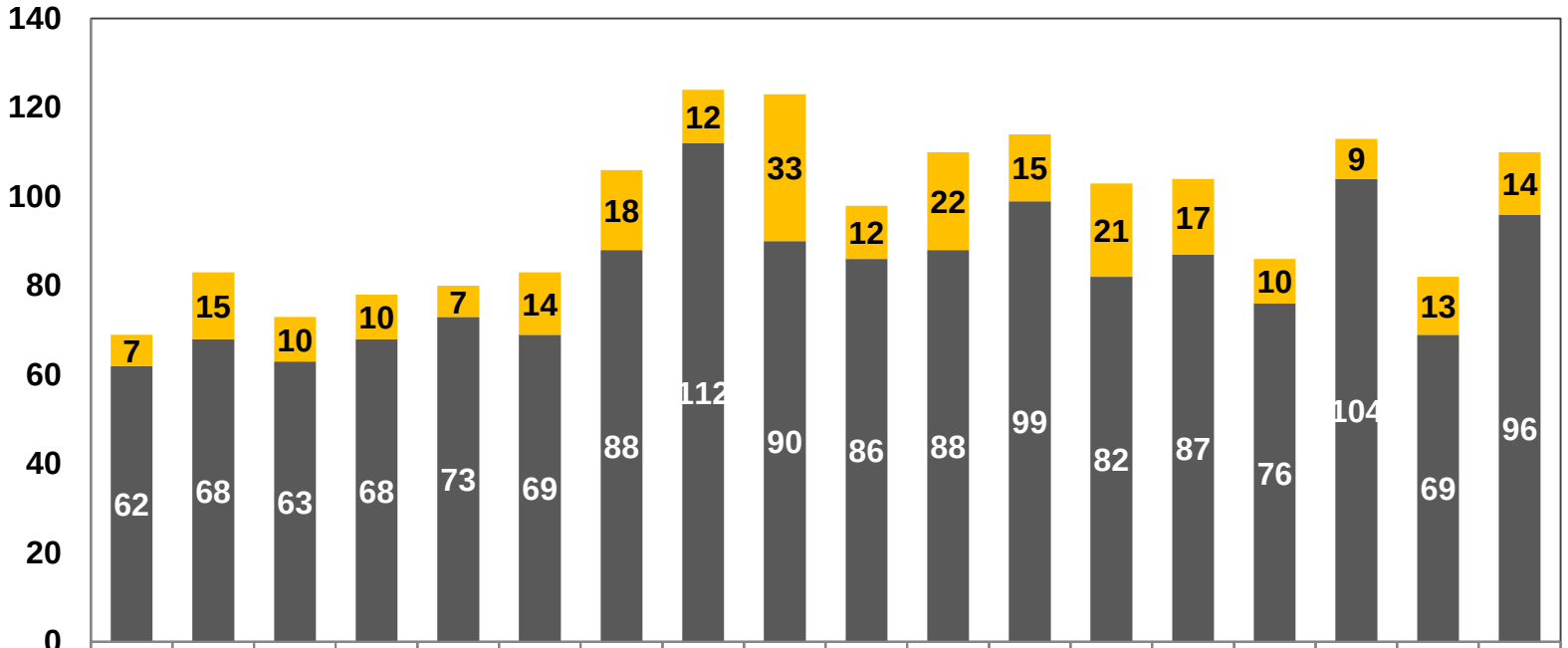
Current Technology Development Platforms

12" Fabs	Production	Development	NVM Type	Process Type
7/10nm	0	2	OTP	FF
14/16nm	1	3	OTP	FF+
28nm	5	9	OTP	LP/HPM, HLP/HPM, LPS
40nm	4	6	OTP, MTP	HV-DDI, LP
55/65nm	11	13	OTP, MTP, Flash	LP, HV-DDI, HV-OLED, DRAM, CIS
80/90nm	5	8	OTP, MTP	HV-DDI, HV-OLED, LP
0.13/0.11um	6	4	OTP, Flash	HV-DDI, BCD, Generic
0.18um	1	0	OTP	BCD

8" Fabs	Development	NVM Type	Process Type
0.13/0.11um	20	OTP, MTP, Flash	HV-DDI, BCD, LP, RF, CIS, LL
0.18/0.16/0.152um	42	OTP, MTP	Generic, LP, LL, MR, HV, Green, BCD
0.25um	1	OTP, MTP	BCD
0.35um	0	OTP	UHV

Quarterly Design Licensing (New Tape Out)

- Total 192 NTO as of H1 2016(406@2015,445@2014, 393@2013, 303@2012)

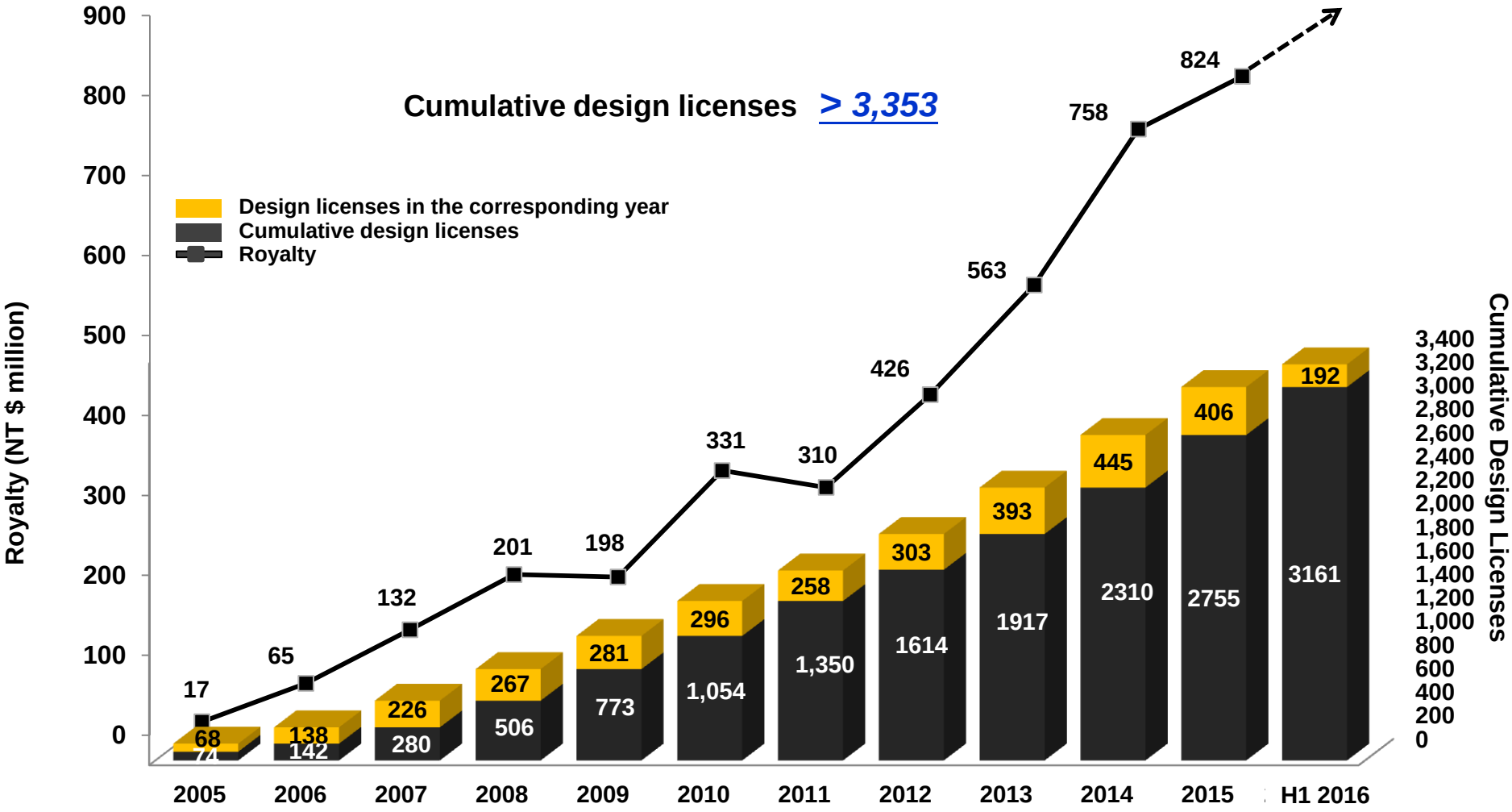


	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2
	2012				2013				2014				2015				2016	
NRE	7	15	10	10	7	14	18	12	33	12	22	15	21	17	10	9	13	14
Usage	62	68	63	68	73	69	88	112	90	86	88	99	82	87	76	104	69	96

Note*: As the applications of MCU at several foundries have gradually entered mass production, and the business model of the main foundry partner which provides green process has shifted to — eMemroy licenses IP cell to the foundry for it to provide direct design service to customers — as the result, the new tape out number of MCU has been affected, but the royalty coming from IP cell usage continues to roll in.

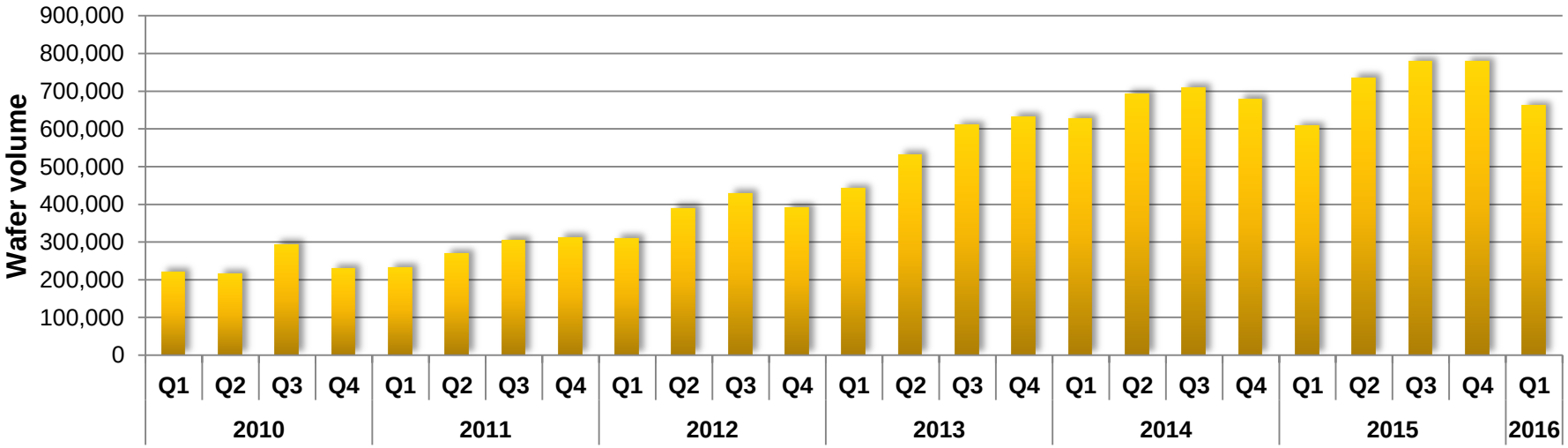
In summary, even the new tape out number of MCU is lower than before; the corresponding wafer output and royalty continue to grow.

Cumulative Licenses Drive Future Royalties



note 1: Due to the 2009 recession, royalty income was down annually 1.5%.
note 2: Pre-payment of royalty fees by a single customer contributed to 2010 annual growth of 67%, causing a drop of 6.3% in the following year, 2011.
note 3: CAGR for 2009-2013 was 30%.

Wafer Production Volume



embedded eMemory IP in T Company ($revenue); * % of Process node in T company total revenue in Q2 2016

	Process node	*% of T	Q2 16	Q1 16	2015	2014
8”	0.25/0.35	3%	* 18.44%	40.91%	33.49%	30.5%
	0.15/0.18	11%	12.32%	13.41%	8.73%	11.9%
	0.11/0.13	2%	43.90%	27.53%	29%	20.8%
12”	90nm	5%	* 11.33%	20.04%	19.85%	16.3%
	65nm	12%	3.76%	2.91%	0.55%	0%
	40/45nm	15%	0%	0%	0%	0%
	28nm	28%	0.41%	0.46%	0.05%	0%
	16/20nm	23%	0	0%	0%	0%
8”		17%	16.39%	20.33%	16.64%	15.6%
12”		83%	1.36%	1.97%	1.87%	1.4%
Total		100%	3.92%	5.09%	4.76%	4.5%

*** Due to Inventory correction of iOS related customers in Q2.**

Outline

- Business Model
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- Q & A

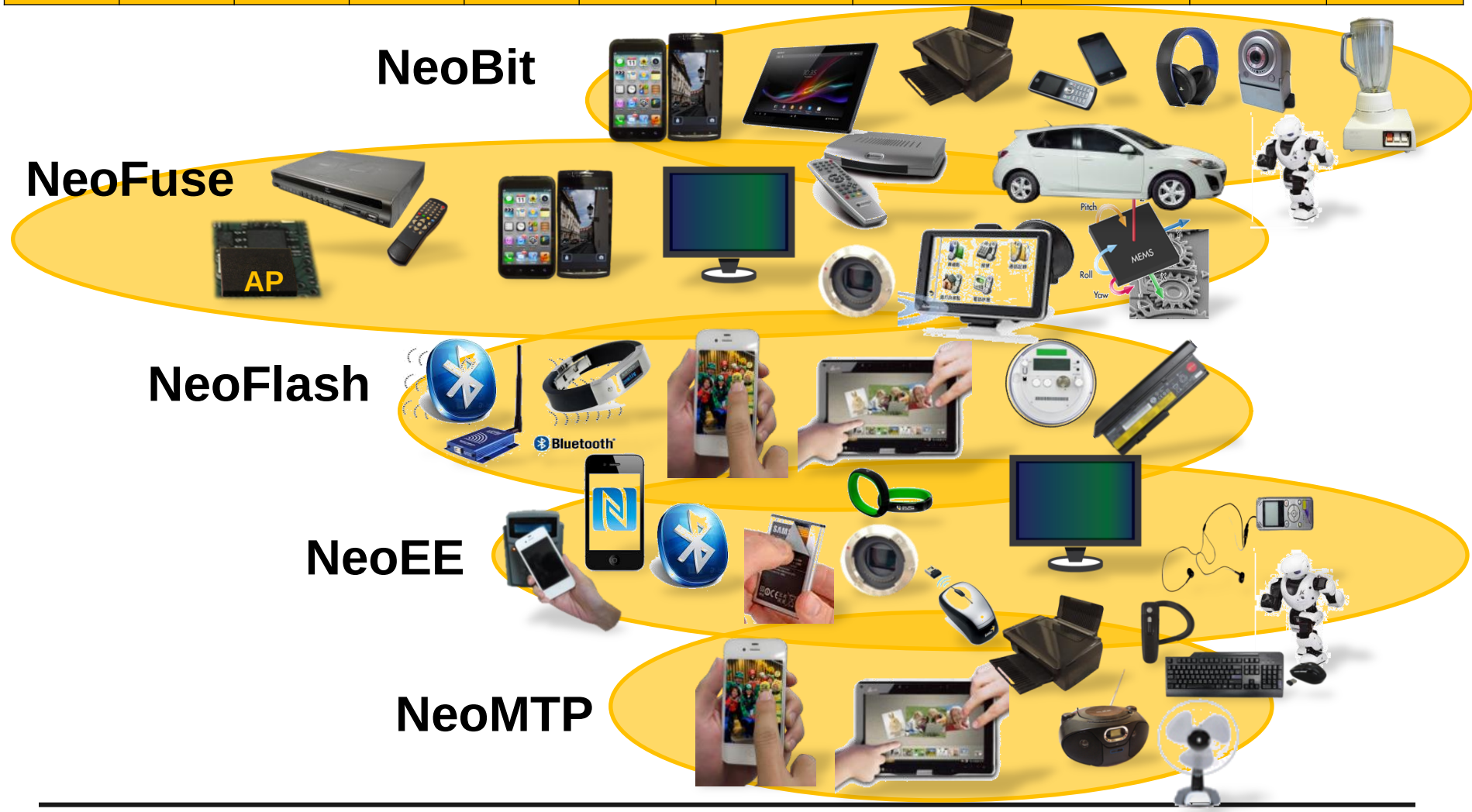
eMemory's NVM Technologies

- **Logic NVM portfolio offers one-stop-shop solution.**
  - Compatible to any process
  - Robust structure
  - Low process cost
  - Competitive macro sizes
  - Easy integration
  - Easy porting

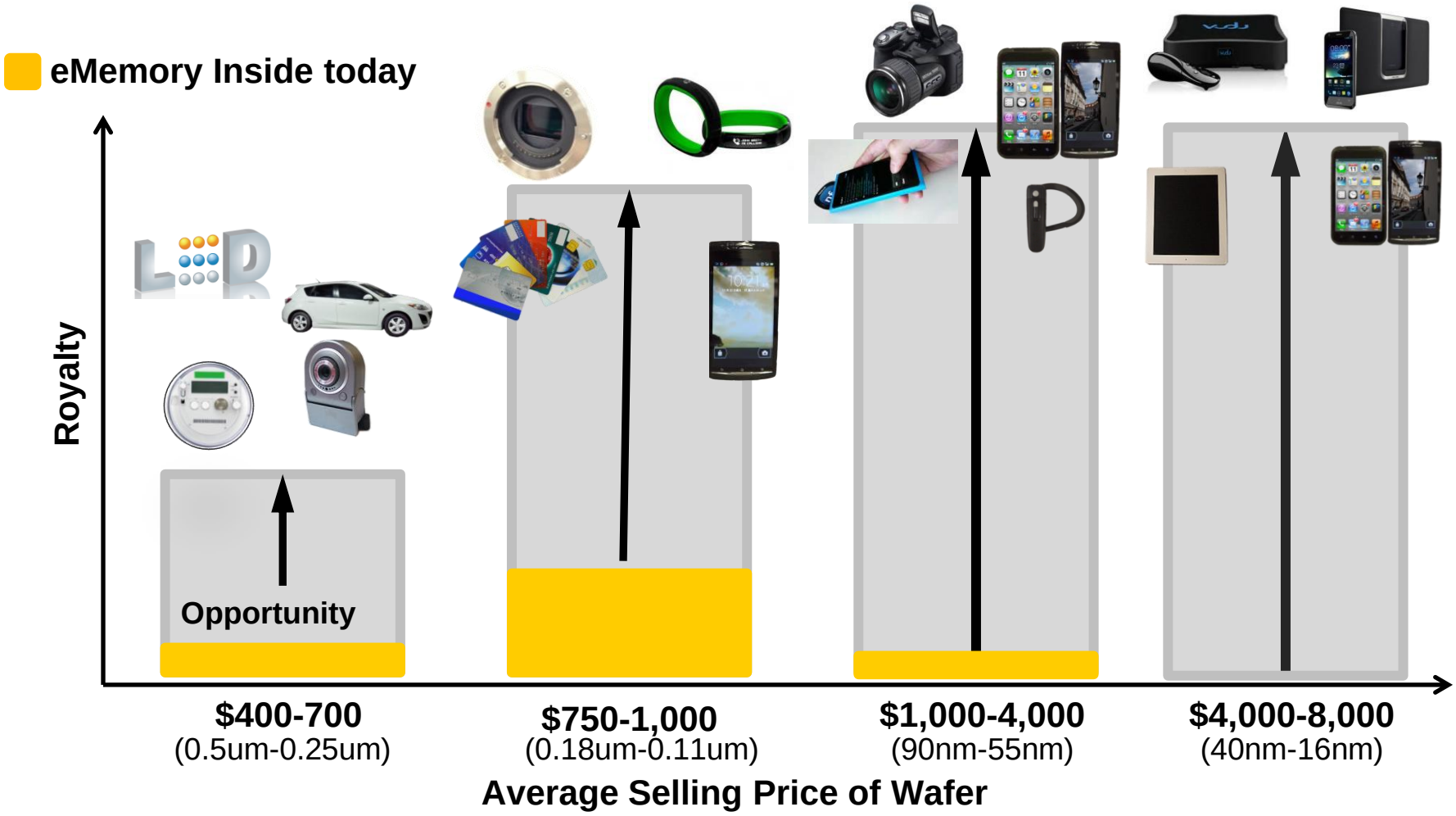
eMemory's NVM Technology	OTP		MTP		
	NeoBit	NeoFuse	NeoFlash	NeoEE	NeoMTP
Product Type	OTP	OTP	Flash	EEPROM	MTP
Endurance (Cycles)	10	10	1K~10K	10K~100K	1K~10K
Additional Mask Steps	0	0	2-3	0	0
Technology	Floating gate	Anti-Fuse	SONOS	Floating gate	Floating gate
Scalability	Simple	Simple	Simple	Simple	Simple
Memory Density	HD < 512Kb GHD < 16Mb	< 4Mb	< 2Mb	< 4Kb	< 512Kb

Applications by Technology

12"								8"		
7nm	10nm	16nm	28nm	40nm	55/65nm	80/90nm	110/130nm	160/180nm	250nm	350nm

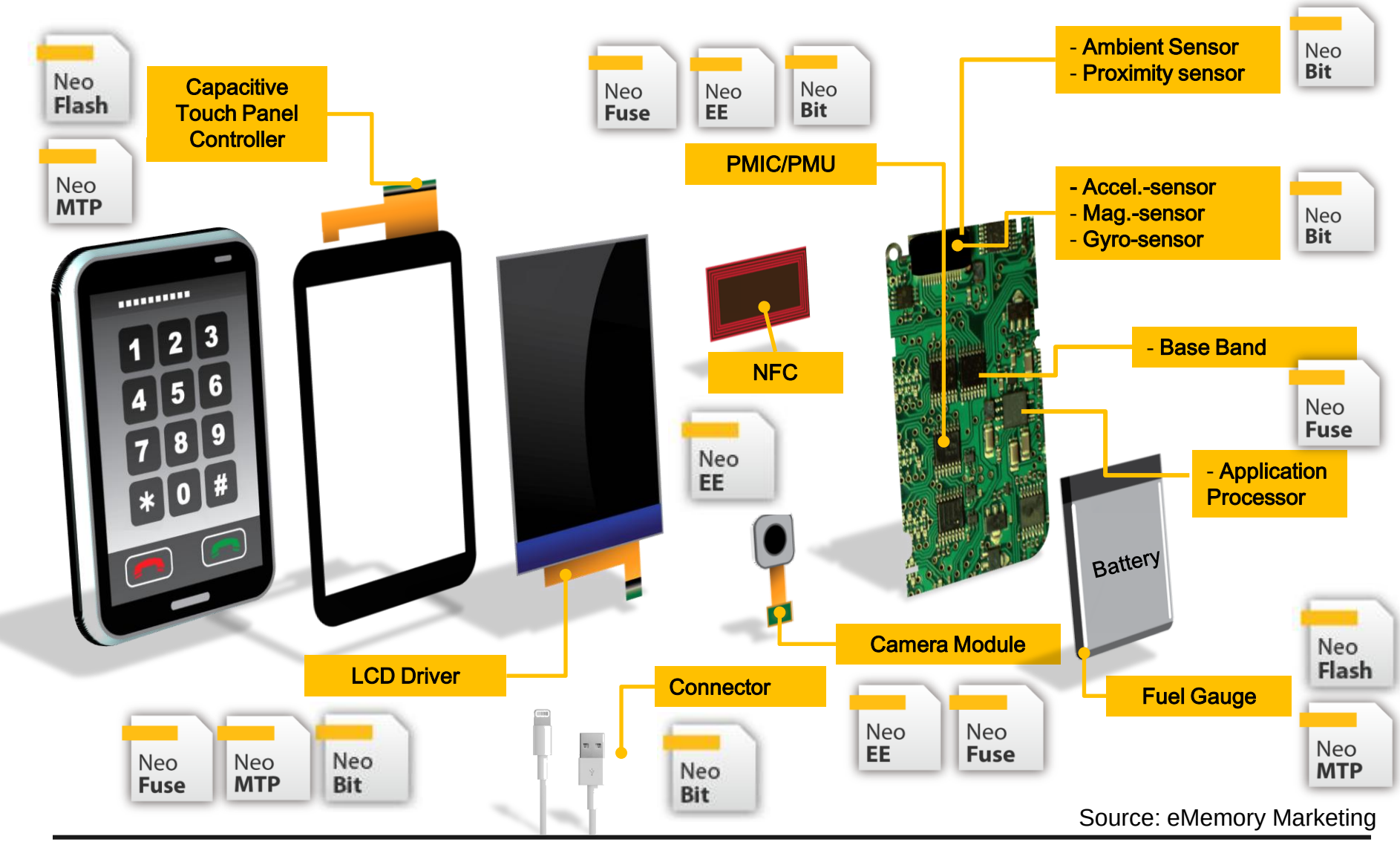


Opportunity at all Price Points



Note: 2.2 million 8" equivalent wafers with eMemory IP were shipped in 2013. (~5% of WW foundry shipment)

eMemory IP in Smart Phone



Source: eMemory Marketing

Benefits from Using eMemory IPs

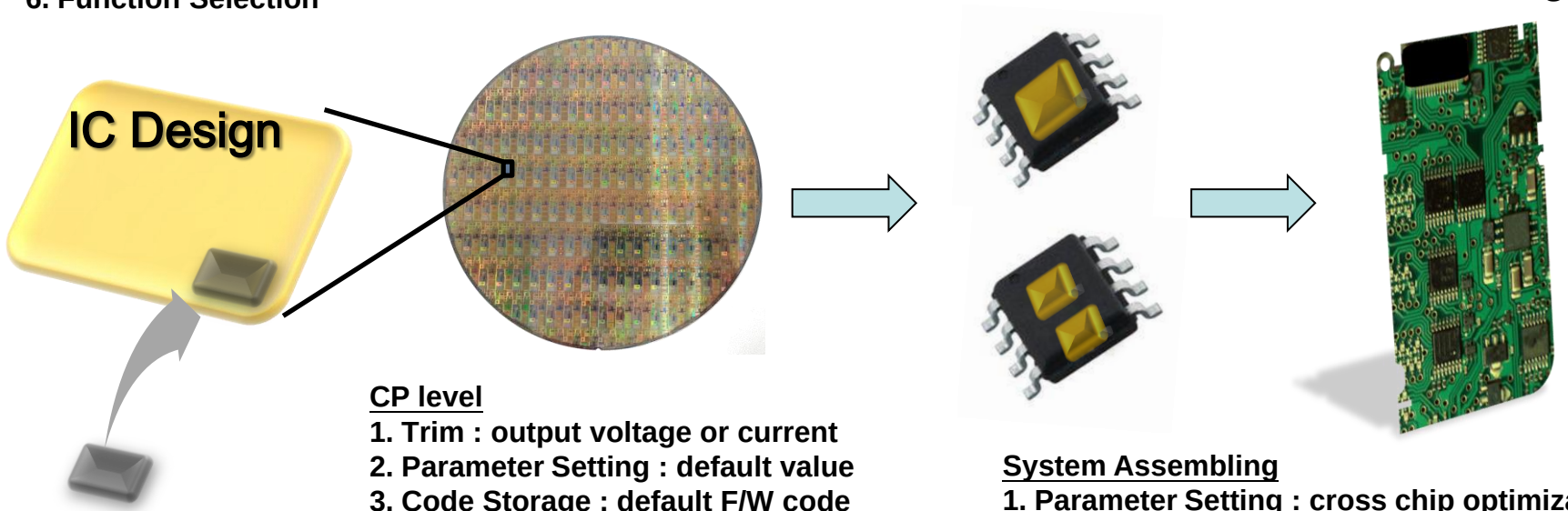
Design-in for
1. Trimming
2. Parameter Setting
3. Code Storage
4. Identification Setting
5. Encryption
6. Function Selection

Package/FT level
1. Trim : SPEC shift
2. Parameter Setting : cross chip optimization
3. Identification Setting : manufacturer resume
4. Function Selection : setting for target market

CP Test

Package/FT

System Assembling



CP level
1. Trim : output voltage or current
2. Parameter Setting : default value
3. Code Storage : default F/W code

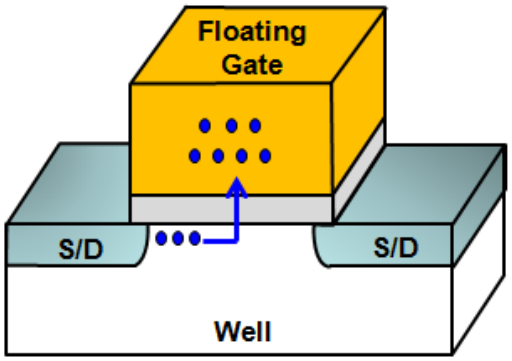
System Assembling
1. Parameter Setting : cross chip optimization
2. Code Storage : F/W code modification
3. Identification Setting : manufacturer resume
4. Encryption : Security algorithm or key storage

Invisibility for Security

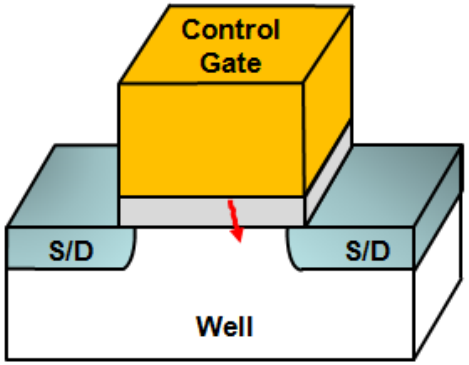
- **Provide “Invisible Hardware Key” for invisible storage**
- **Prevent reverse-engineering to detect content of security key**
- **Protect firmware and hardware of ICs from pirating**
- **Extend & protect customer’s business**

eFuse Key: Data is easily observed

Invisible Hardware Key : Data is hard to be detected



Floating Gate



Anti-Fuse

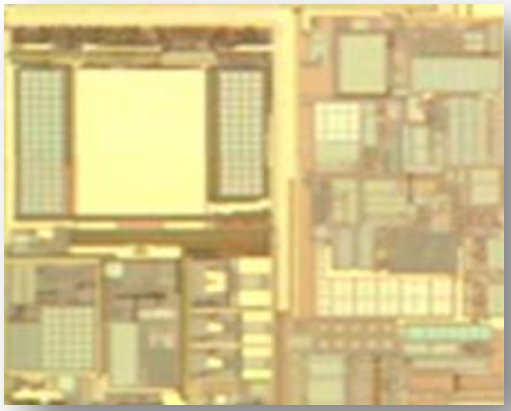
Security & Protection

Authorized Product

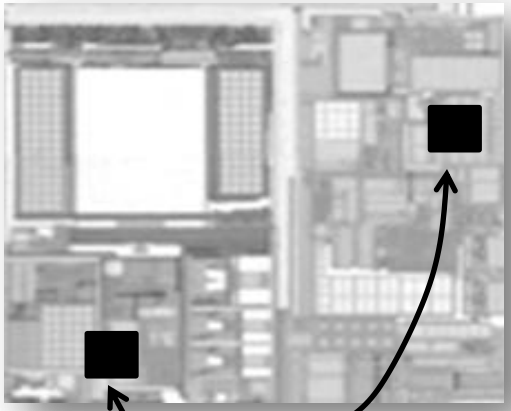
Fake Product

reverse copy

re-produce

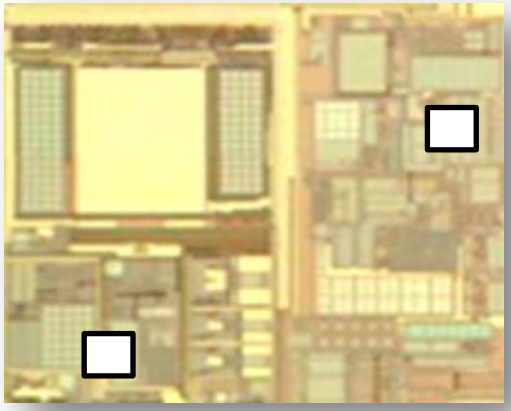


without protection



reverse copy

re-produce

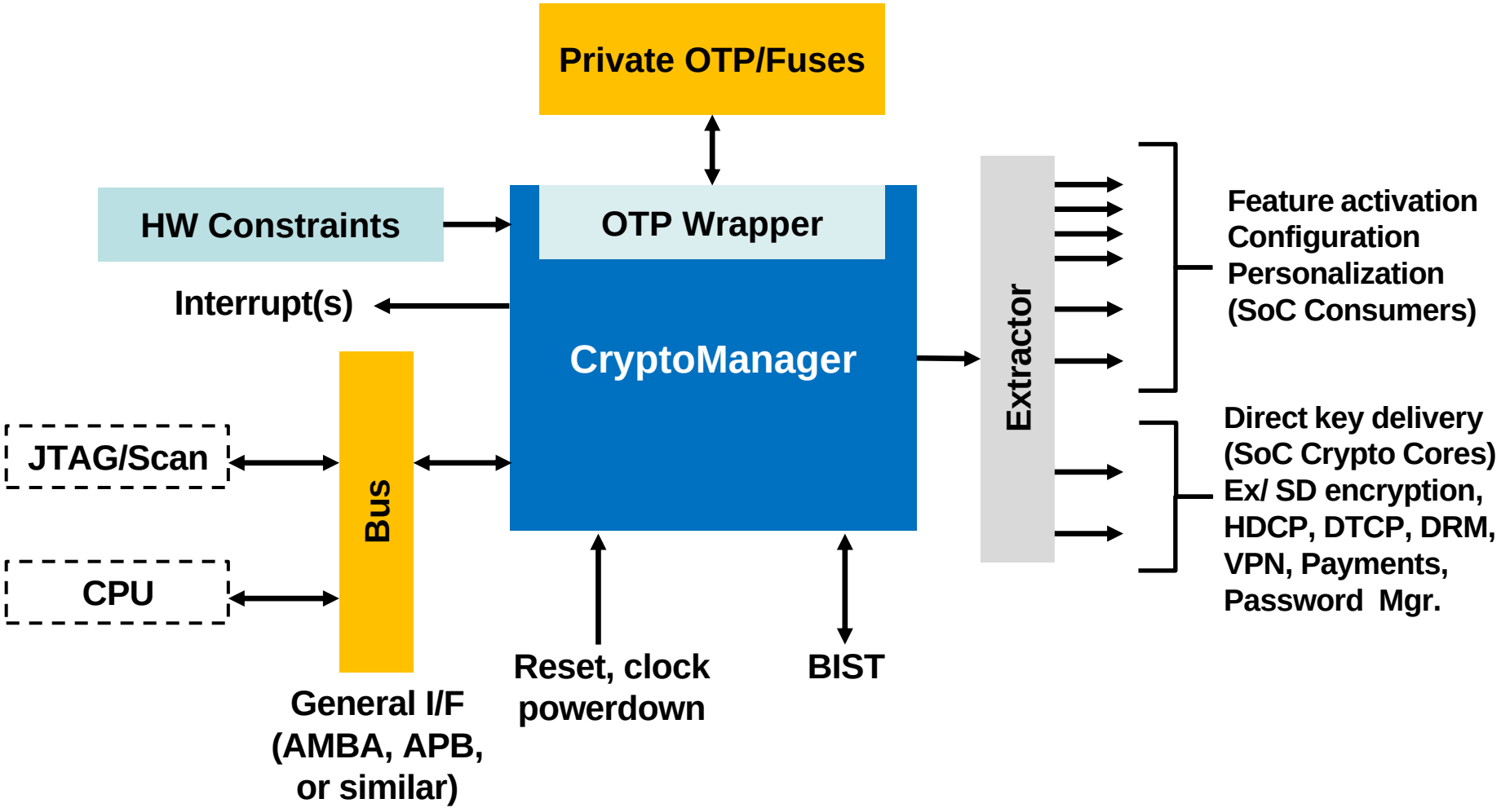


with protection

Security IP/Code by Authorized Use

Can NOT Work w/o Security IP/Code

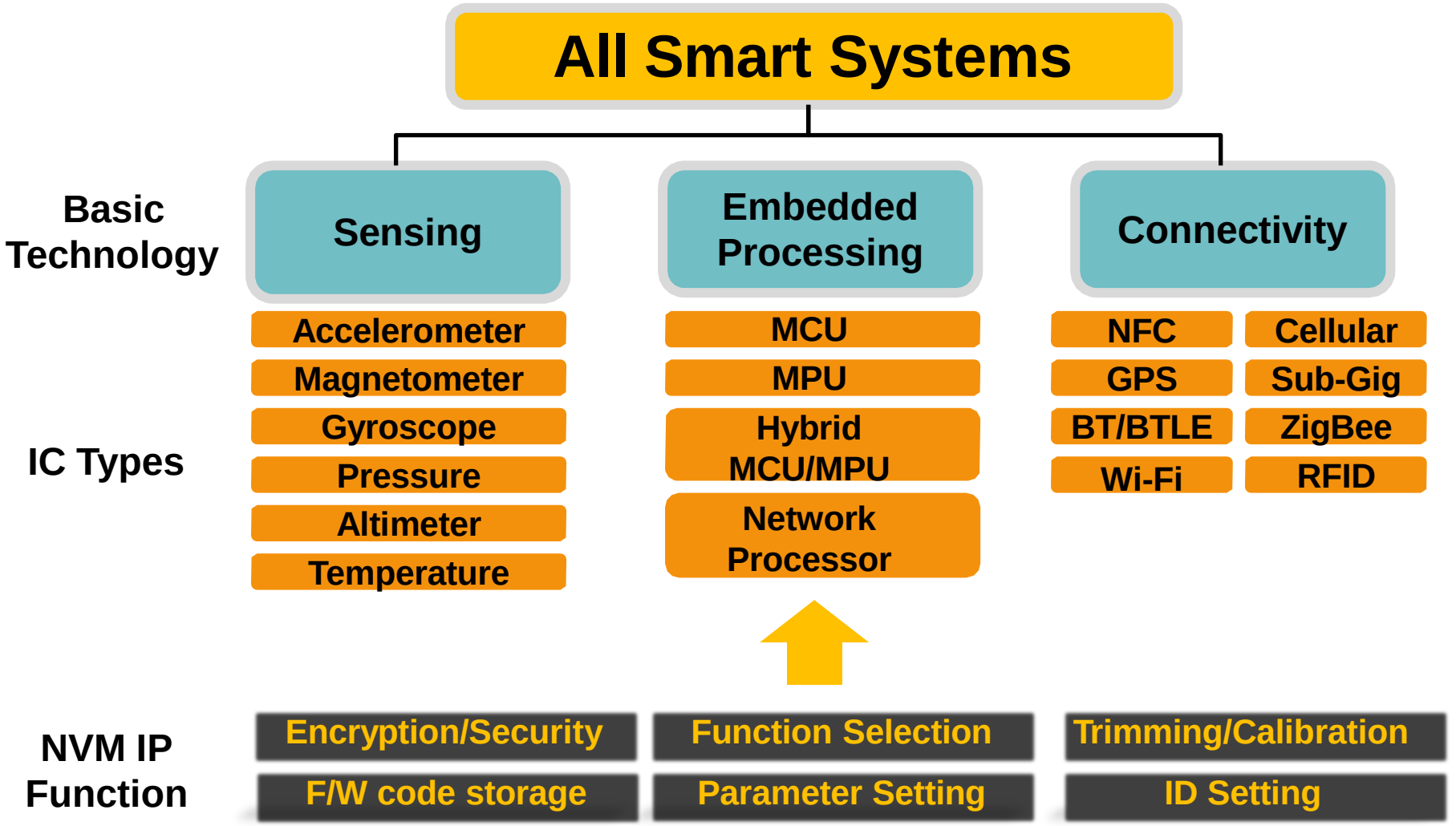
OTP for security storage



Source： Rambus crypto manager platform

Security with eMemory IPs

NVM IP Demand in IoT

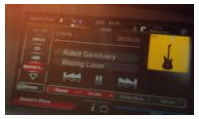


Autotronics with eMemory IPs

Intelligent drive
Distronic system

Neo **Bit** Neo **Fuse**

Infotainment system

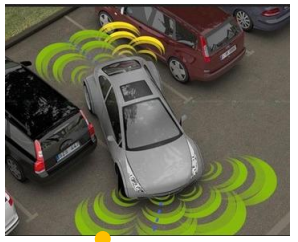


Neo **Bit** Neo **Fuse**

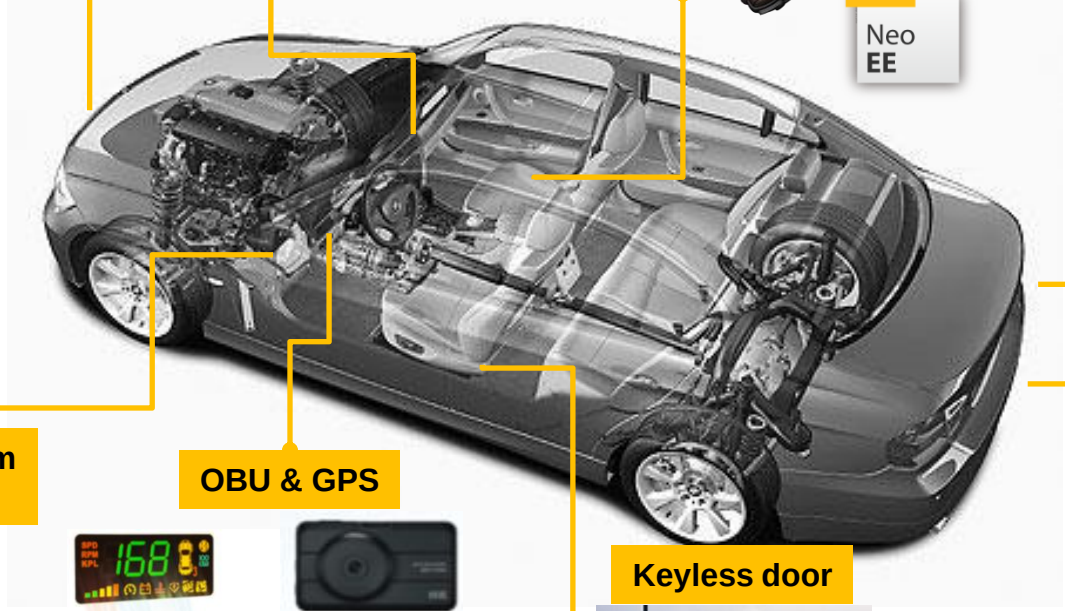
Sensor system

Neo **Bit** Neo **EE**

Auto parking system



Neo **Bit** Neo **Fuse**



Blind Spot Warning System
Cockpit System

Neo **Bit** Neo **Fuse**

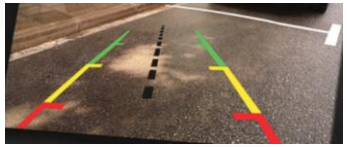
OBU & GPS

Neo **Bit** Neo **Fuse**

Keyless door

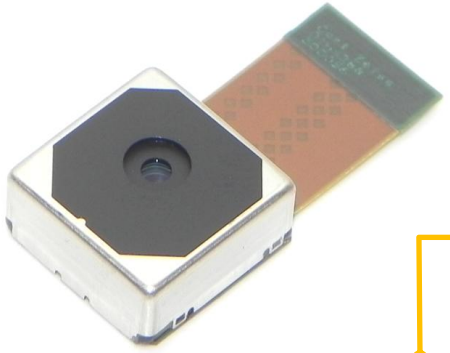
Neo **Bit** Neo **EE**

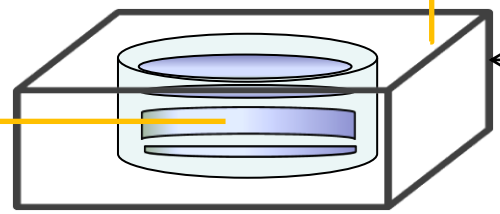
Rear view system

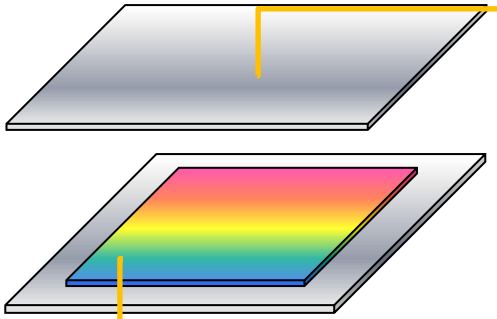


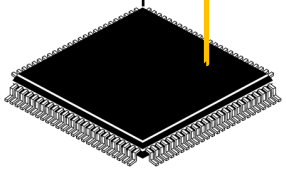
Neo **Bit** Neo **Fuse**

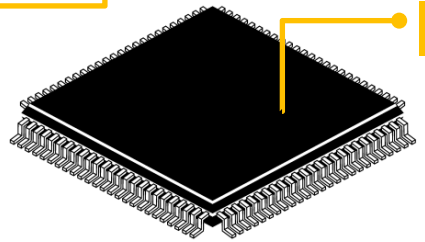
Imager Module with eMemory IPs











VCM

Lens

IR Cut Filter

AF/OIS Controller
(VCM Driver)

Neo Fuse

Neo Bit

Neo EE

Neo MTP

Image Sensor

Neo Fuse

Neo Bit

ISP

Neo Fuse

Neo Bit

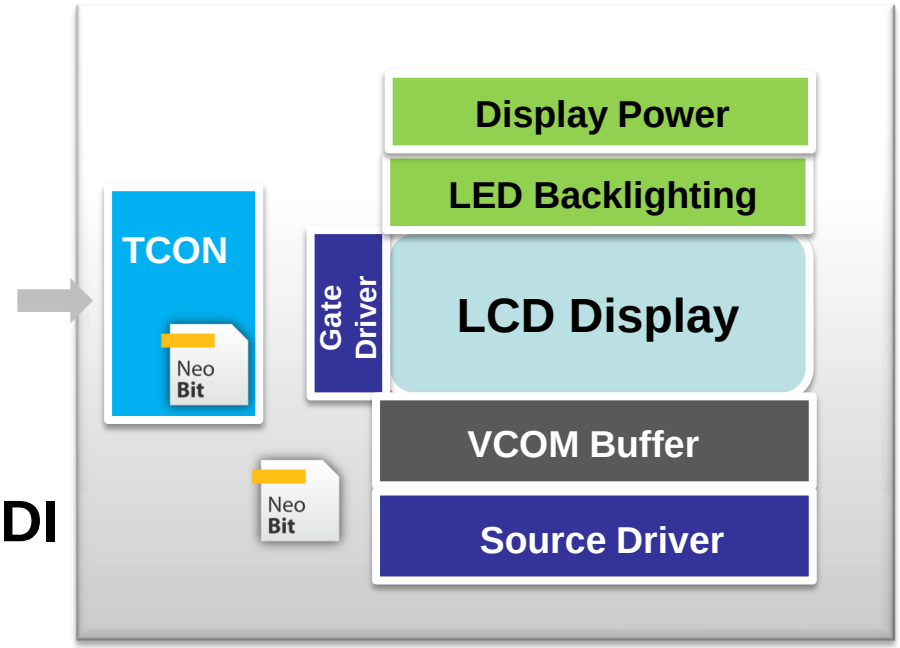
Neo EE

Neo MTP

Advanced LCD Driver ICs

Process Technology : 0.11um HV/80nm HV/55nm HV

I/F
(LVDS, MIPI,…)

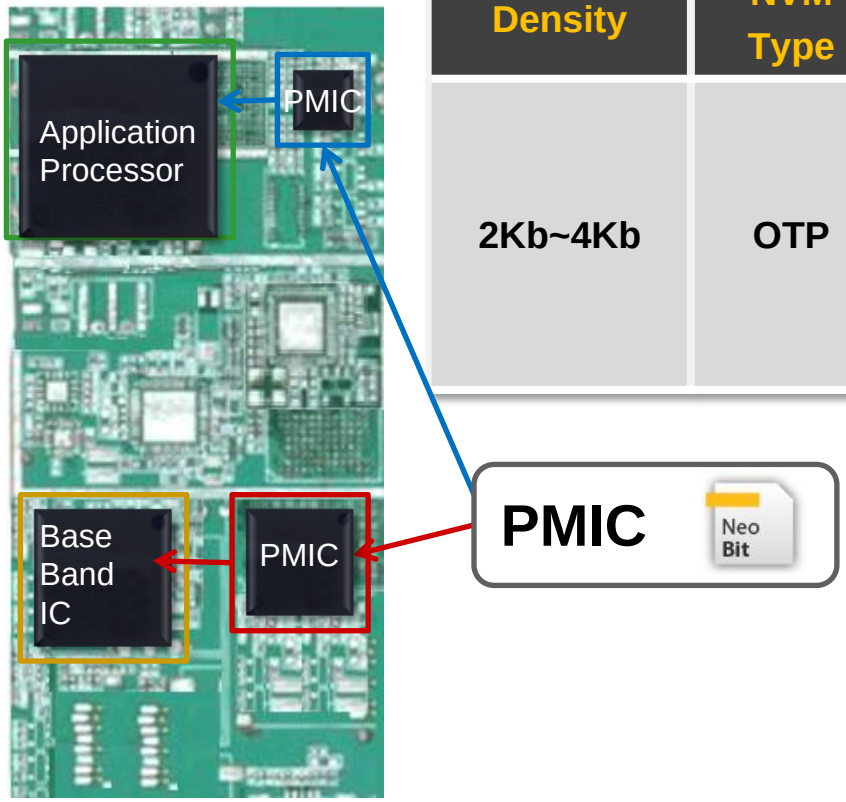


DDI

Density	Endurance	NVM Type	Purpose	NVM Usage
2K8~4K8	1	OTP	Trimming	1. Accuracy enhancement 2. Mismatch cancellation
			Code Storage	1. Gamma Correction Table 2. Timing Control Pattern 3. Color Engine Enhancement

Power Management ICs for Baseband and Application Processor

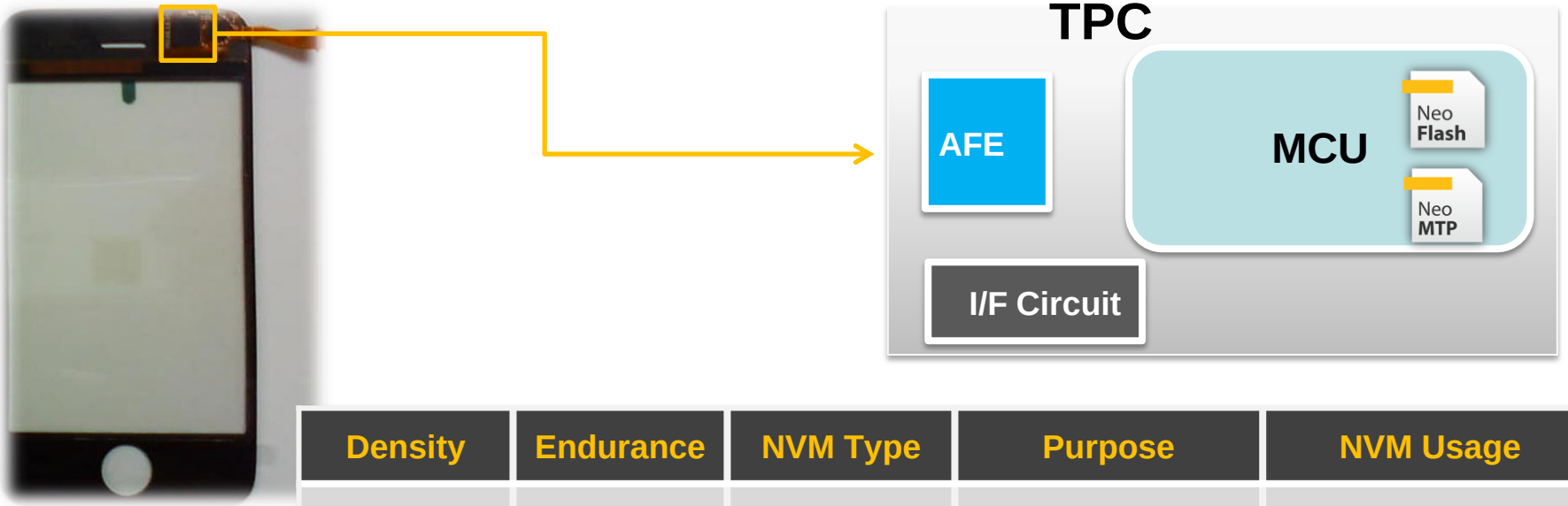
Process Technology : Advanced 0.25um BCD/ 0.18um BCD/ 0.13um BCD
Mature 0.18um/0.16um/0.152um Logic



Density	NVM Type	Purpose	NVM Usage
2Kb~4Kb	OTP	Trimming	DC/DC, Bandgap
		Parameter Setting	Design flexibility & Performance optimization
		Code Storage	Start-up behavior & smart power saving algorithm

Touch Panel Controller ICs

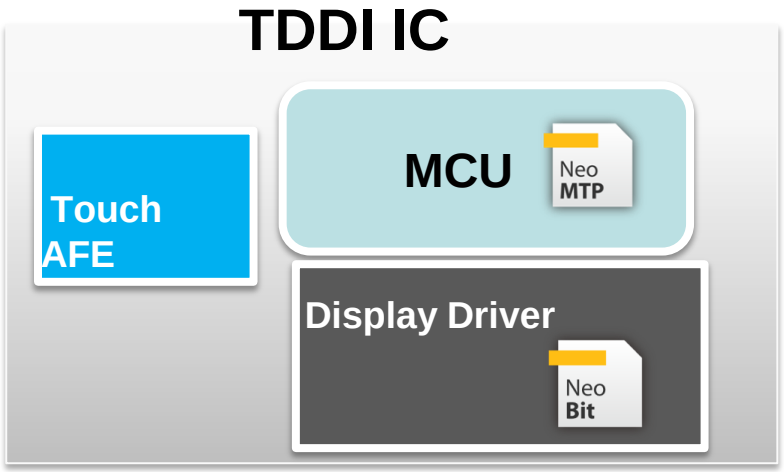
Process Technology : 0.16um HV/0.11um G



Density	Endurance	NVM Type	Purpose	NVM Usage
16K8~32K8	<1000	MTP	Code Storage	F/W code
			Parameter setting	Customized model and performance optimization

In-Cell Touch Panel Controllers ICs

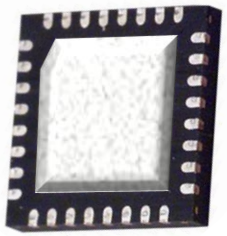
Process Technology : 0.11um HV/80nm HV/55nm HV

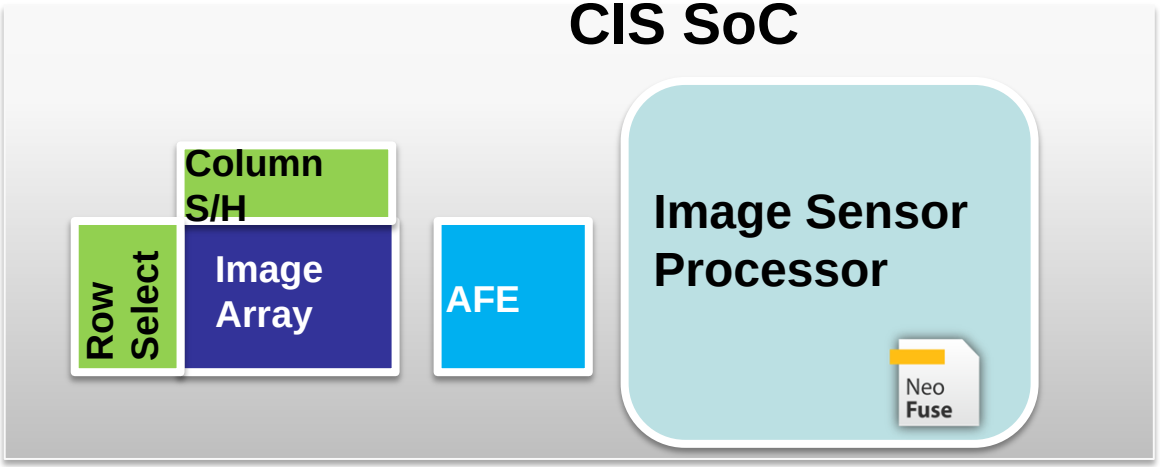


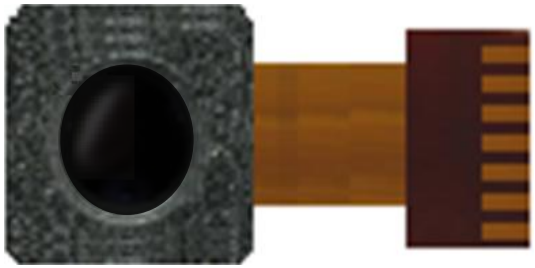
Density	Endurance	NVM Type	Purpose	NVM Usage
2K8~4K8	1	OTP	Trimming	Accuracy
			Code Storage	Gamma Table
16K8~32K8	<1000	MTP	Code Storage	Touch F/W Code
			Parameter setting	Performance Optimization

CMOS Image Sensor

Process Technology : 0.11um CIS/90nm CIS/65nm CIS



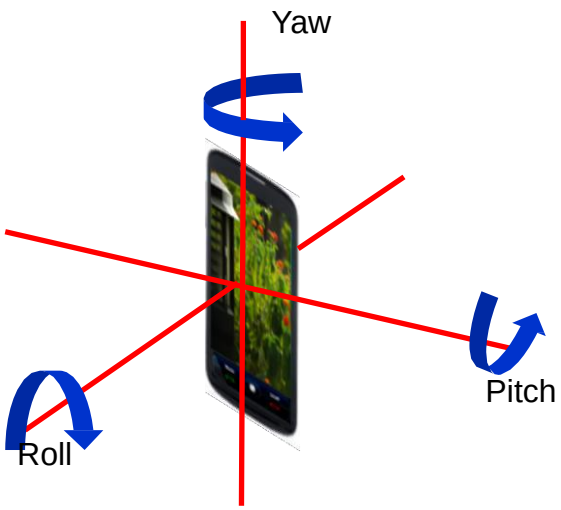


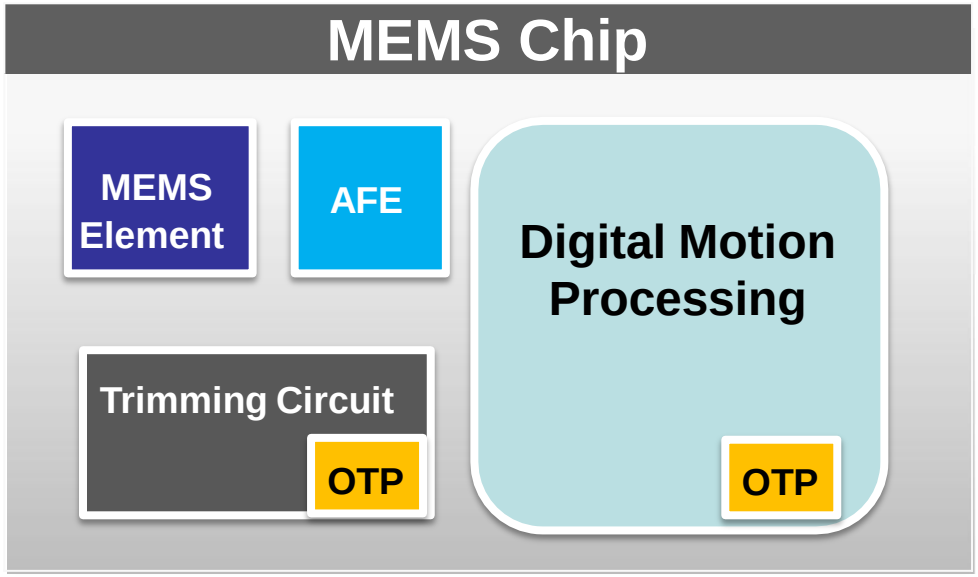


Density	Endurance	NVM Type	Purpose	NVM Usage
2Kb~4Kb	1	OTP	Identification Setting	Product Code
			Parameter Setting	Start-up Initial Setting
32K8	1	OTP/ROM	Code Storage	Boot Load

MEMS

180/160/15x nm HV/Logic for MEMS Controller





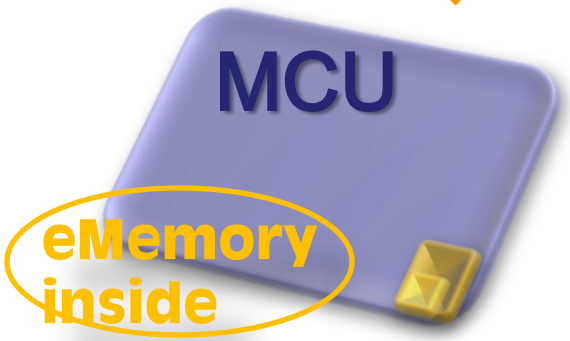
Density	NVM Type	Purpose	NVM Usage
2Kb~4Kb	OTP	Trimming	Factory trimming
		Parameter Setting	Signal filtering
		Code Storage	Geometric computation

Replacement of Embedded Flash for Competitiveness Improvement

product design & manufacturing by embedded Flash
Logic Process + 10 Masks

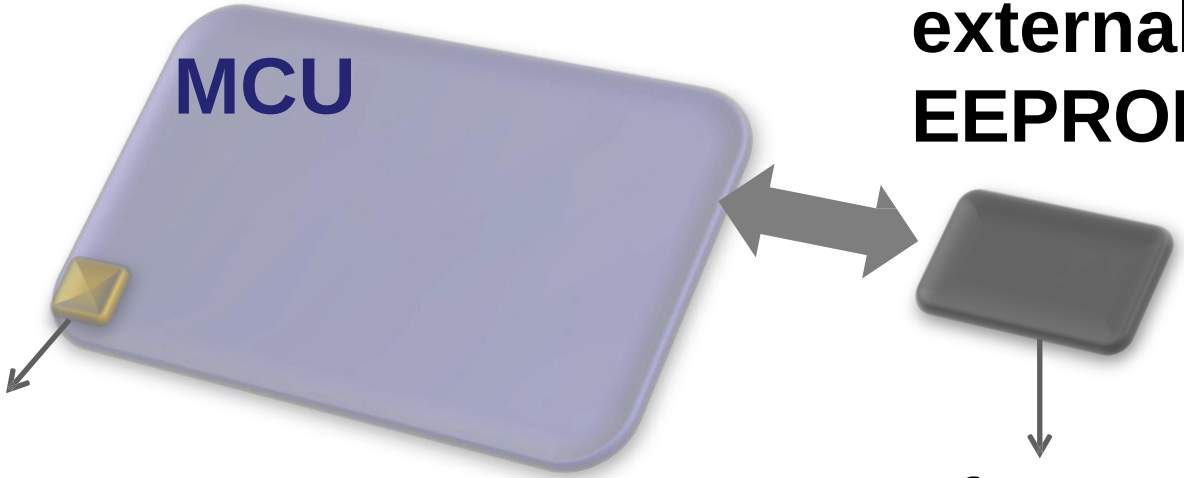
30% more cost reduction

wafer cost & testing time



product design & manufacturing by Embedded Logic NVM (OTP/MTP) Logic Process

MCU Applications with EEPROM

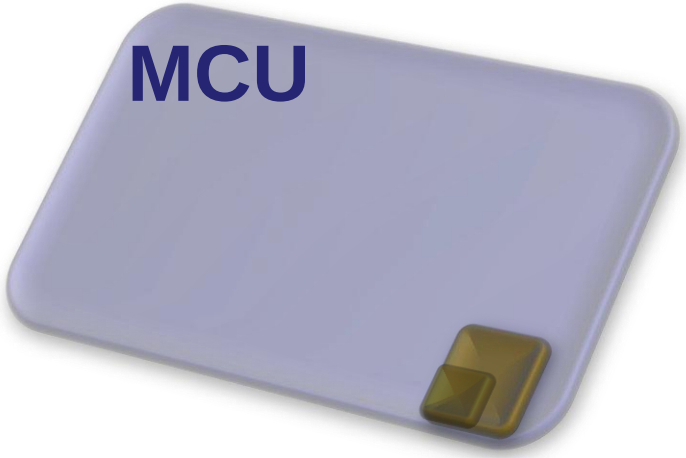


One-time storage for ID, trimming, encryption…

EEPROM for user data, parameter setting, system function…

NeoBit + NeoEE

Hybrid NVM solution (NeoBit + NeoEE) with customized SPEC & optimized size



- **One single IP by integration of NeoBit & NeoEE**
- **Help for system size reduction**

Wafer Demand by IC Type

IC Type	Equa to 8-inch wafer (K)
AP	5740
PMU	5255
Base Band controller	2945
Smart card controller	2683
Fingerprint	2500
CIS sensor	2215
LCD driver (int with TCON)	1955
Gauge IC	708
TV controller	619
Touch panel controller (C)	602
Connectivity	463
STB controller	348
DC-DC/AC-DC	239
Wifi controller	231
Accelator sensor controller	166
LED driver	140
Light snesor	126
Gyroscope sensor controller	120
BT controller	107
TAG IC	104
MCU (8bits, LV/3.3V)	90
MCU (8bits, pure 5V)	88
ISP	82
DVD controller	67
P-Gamma	47
NB CAM controller	38
Pressure sensor controller	23
Touch pad controller	16
PC CAM controller	14
Touch panel controller (R)	3
TCON (w/o driver)	3
Speech controller	0

2015 Q3 updated

Outlook for Q3 and Beyond

- iOS related applications will increase wafer production in Q3 after experiencing an inventory correction in previous quarters, and are expected to see a substantial increase in royalty contribution in Q4.
- With more customers ramping up production and expanding into new applications, PMIC related products will maintain strong growth momentum in the coming quarters.
- 55nm TDDI continues volume production.
- Fingerprint customer started wafer production in Q2 and contributed 4% of total July royalty. We expect more fingerprint customers to ramp up production in Q3, resulting in further contribution to royalties in the following quarters.

Outlook for Q3 and Beyond

- 28nm DTV applications will increase volume production in 2H of 2016. 2 more STB customers have taped-out in the 1H of 2016.
- 7 process platforms for OLED are under qualification at different foundries. There were 2 tape-outs for OLED drivers in second quarter and more tape-outs expected in 2H.
- We expect 2 NRE designs and tape outs in 16nm FFC in 2H of 2016.
- NeoPUF, our new technology for security applications is expected to tape-out IP in September.
- Automotive applications continue platform build with further tape outs for European and Japan customers.

Key Growth Drivers

Growth in application per mobile devices	• More chip applications per smartphone/tablet product.
Growth into more markets	• From consumer electronics and mobile devices to wearable devices. • Adding new NVM product lines further enable more product applications.
Growth in advanced technology	• Higher royalty per wafer is contributed from more advanced technology nodes.
Great IoT era	• Embedded Logic NVM will be a must.

Q & A

ememory

Embedded Wisely, Embedded Widely